



**12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

**PCN#20191211002.2**

**Qualification of TI Malaysia as an additional AT site for the AMC1200STDUBRQ1  
Change Notification / Sample Request**

**Date:** December 13, 2019  
**To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

If samples or additional data are required, requests must be received within 30 days of acknowledgement as samples are not built ahead of the change. You may contact the PCN Manager or your local Field Sales Representative to acknowledge this PCN and request samples or additional data.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team  
SC Business Services

**20191211002.2**  
**Change Notification / Sample Request**  
**Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
AMC1200STDUBRQ1	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20191211002.2		<b>PCN Date:</b>	Dec 13 2019									
<b>Title:</b>	Qualification of TI Malaysia as an additional AT site for the AMC1200STDUBRQ1												
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services										
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Jun 10 2020	<b>Estimated Sample Availability:</b>	Date provided at sample request										
<b>Change Type:</b>													
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site								
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material								
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process								
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site								
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials								
				<input type="checkbox"/>	Wafer Fab Process								
<b>PCN Details</b>													
<b>Description of Change:</b>													
<p>Texas Instruments is pleased to announce the qualification of TI Malaysia as an additional assembly site for the AMC1200STDUBRQ1. Current assembly site and Material differences are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>Hana</th> <th>MLA</th> </tr> </thead> <tbody> <tr> <td>Mold Compound</td> <td>SID#450265</td> <td>4221499</td> </tr> <tr> <td>Mount Compound</td> <td>SID#400180</td> <td>4211470</td> </tr> </tbody> </table>						Hana	MLA	Mold Compound	SID#450265	4221499	Mount Compound	SID#400180	4211470
	Hana	MLA											
Mold Compound	SID#450265	4221499											
Mount Compound	SID#400180	4211470											
<b>Reason for Change:</b>													
Continuity of Supply													
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>													
None													
<b>Anticipated impact on Material Declaration</b>													
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>										

<b>Changes to product identification resulting from this PCN:</b>			
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>
Hana	HNT	THA	Ayutthaya
<b>MLA</b>	<b>MLA</b>	<b>MYS</b>	<b>Kuala Lumpur</b>
Sample product shipping label (not actual product label)			



MADE IN: Malaysia  
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO:USA  
(22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

AMC1200STDUBRQ1



TI Information  
Selective Disclosure

**Automotive New Product Qualification Summary  
(As per AEC-Q100 and JEDEC Guidelines)**

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: AMC1200STDUBRQ1
<b>Test Group A – Accelerated Environment Stress Tests</b>							
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	Level 3-260C	1 Fail (1)
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST, 130C/85%RH	96 Hours	3/231/0
AC	A3	JEDEC JESD22-A102	3	77	Autoclave 121C	96 Hours	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle, -65/150C	500 Cycles	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	60	Post Temp Cycle Bond Pull, 500 Cycles	Wires	1/30/0
PTC	A5	JEDEC JESD22-A105	1	45	Power Temperature Cycle	1000 Cycles	N/A
HTSL	A6	JEDEC JESD22-A103	1	45	High Temp Storage Bake 150C	1000 Hours	1/45/0
<b>Test Group B – Accelerated Lifetime Simulation Tests</b>							
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test, 150C	300 Hours	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate, 125C	24 Hours	3/840/0
EDR	B3	AEC Q100-005	3	77	NVM Endurance, Data Retention, and Operational Life	-	N/A
<b>Test Group C – Package Assembly Integrity Tests</b>							
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear, Cpk>1.67	Wires	1/30/0
WBP	C2	MIL-STD883 Method 2011	1	30	Bond Pull, Cpk>1.67	Wires	1/30/0
SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability w Bake Precon	Pb Free Solder	3/36/0
SD	C3	JEDEC JESD22-B102	1	15	Surface Mount Solderability w Bake Precon	Pb Solder	3/36/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	3/30/0
<b>Test Group E – Electrical Verification Tests</b>							
CDM	E3	AEC Q100-011	1	3	ESD - CDM	1500 V	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distribution	Cpk>1.67	3/90/0

**A1 (PC): Preconditioning:**

Performed for THB, Biased HAST, AC, uHAST, TC & PTC samples, as applicable.

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40°C to +150°C

Grade 1 (or Q): -40°C to +125°C

Grade 2 (or T): -40°C to +105°C

Grade 3 (or I): -40°C to +85°C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold: HTOL, ED

Room/Hot: THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room: AC/uHAST

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

**IMPORTANT NOTICE AND DISCLAIMER**

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.